



MIT-019-01-F-D

MIT-038-01-F-D

MIT-057-01-L-D

(0,635 mm) .025"

MIT SERIES

MIXED TECHNOLOGY HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIT

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze

Plating:
Au or Sn over 50µ" (1,27 µm) Ni
Operating Temp Range:
-55°C to +125°C

Voltage Rating:
275 VAC
Max Cycles:
100

RoHS Compliant:
Yes

Processing:
Lead-Free Solderable:
Yes

SMT Lead Coplanarity:
(0,10 mm) .004" max (019-057)
Board Stacking:
For applications requiring more than two connectors per board contact ipg@samtec.com

Board Mates:
MIS

Cable Mates:
MICD



• Mixed technology footprint

Integral metal plane for power or ground

76 signal lines per linear inch

Choice of mated heights

Polarized

MIT/MIS 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	9.5 GHz / 19 Gbps

*Performance data includes effects of a non-optimized PCB.
Performance data for other stack heights and complete test data available at www.samtec.com?MIT or contact sig@samtec.com

OTHER SOLUTIONS

- Board Spacing Standoffs. See SO Series.

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 11 mm, 16 mm, 18,75 mm and 22 mm stack height
- 30µ" (0,76 µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row
- Edge Mount

Contact Samtec.



-019, -038, -057
(38 total positions per bank)

Specify LEAD STYLE from chart

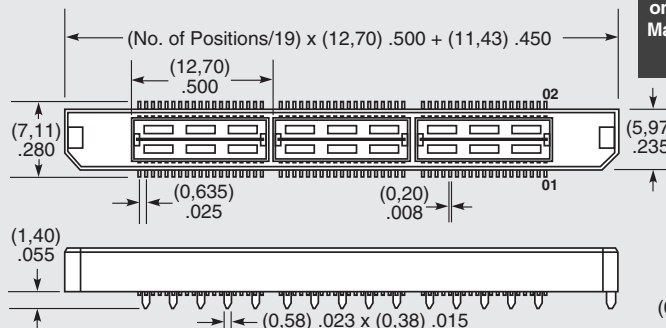
-F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

-L
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

-C*
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, 10µ" (0,25 µm) min Au over 50µ" (1,27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

-K
= (7,00 mm) .275" DIA Polyimide film Pick & Place Pad

-TR
= Tape & Reel



STACK HEIGHTS		
LEAD STYLE	A	MATED HEIGHT
-01	(4,27) .168	(5,00) .197
-02	(7,26) .286	(8,00) .315

Processing conditions will affect mated height.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press fit) for added retention to PCB.